Model KAC375-250AG

Termination, Chip

Frequency Range: DC to 3.0 GHz, Power: 150 Watts

Features

- High Power
- Thick Film Design
- Low VSWR
- Optimized for Heat Sink Mount

This high power device is designed to dissipate power in RF circuits when mounted to an appropriate heat sink. The terminations provide a low VSWR under maximum power conditions.

Technical Specifications

Parameter	Value
Frequency Range	DC to 3.0 GHz
Impedance	50 ±5% Standard
Power Handling*	150 Watts Avg. Derated Linearly to 0 Watts @ +150°C
VSWR	1.10:1 Max.
Temperature Range	-55°C to +150°C

Material

Feature	Material
Substrate	Aluminum Nitride
Resistor Material	Proprietary Thick Film
Terminal Finish	Silver– *(See "How to Order" for tinning & other options)*

*Mounting surfaces shall not exceed 100°C. Max.

How to Order

KACT375-250AG-XXXX Y

Terminal Options
□ = Silver over Nickel
T = Tin Lead Solder
H = Lead Free Solder

Ohm Value
50R0 = 50 Ohms
1000 = 100 Ohms

Tolerance
J = ±5%

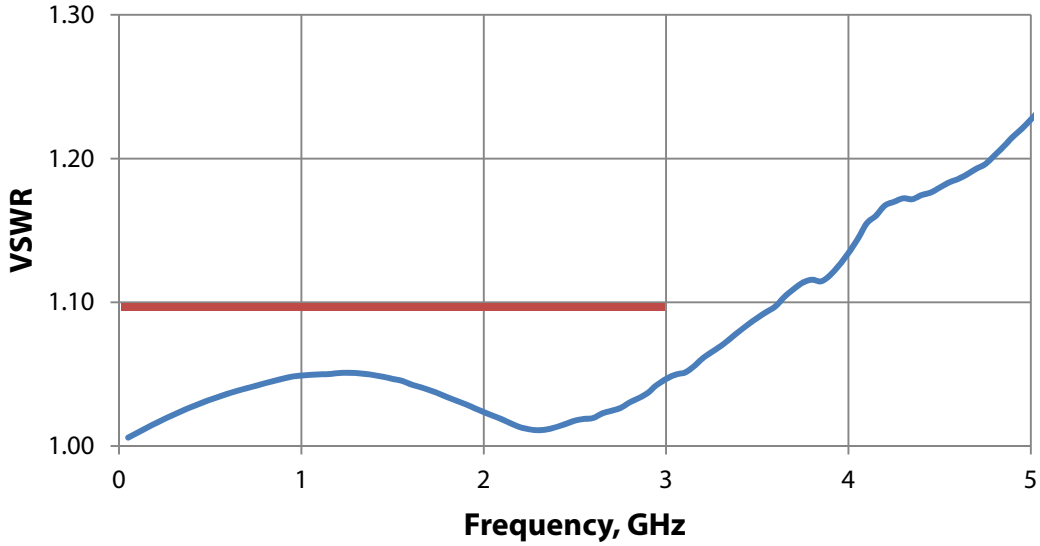
Ordering Examples

Model Number: KAC375-250AG-50R0J
Silver over Nickel Terminals, 50 Ohms; 5%

Model Number: KACH375-250AG-50R0J
Lead Free Solder Terminals, 50 Ohms; 5%

Performance Characteristics

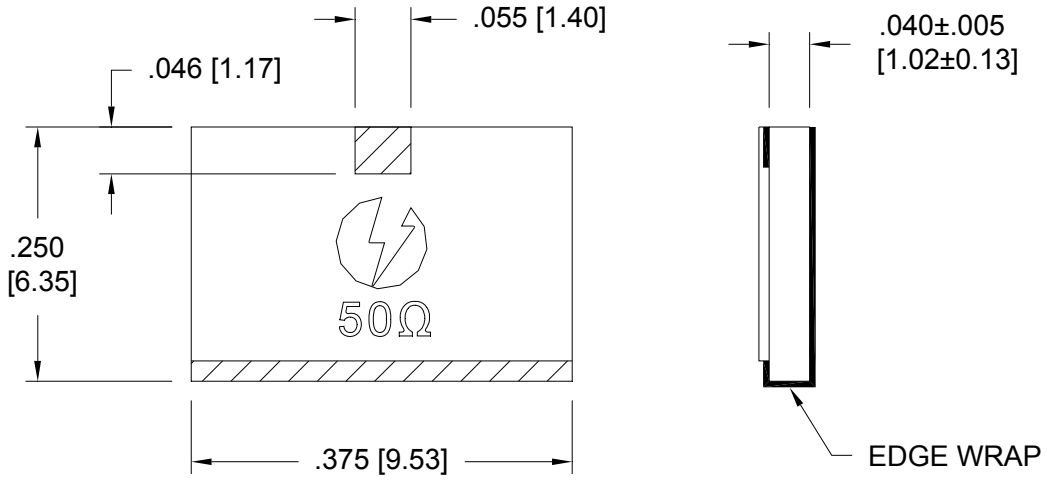
Typical Performance



Physical Dimensions

Model Number: KAC375-250AG-50R0J shown

Tolerance: .XXX" - ±.010"



Dimensions are for substrate only and do not include terminal thickness or optional tinning thickness.

Note: Dimensions in Brackets [ ] are expressed in Millimeters and are for reference only